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PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q65269

Katsumi KIKUCHI, et al.

Appln. No.: 09/894,123

Group Art Unit: 2823

Confirmation No.: 5729

Examiner: William D. Coleman

Filed: June 29, 2001

For: SEMICONDUCTOR PACKAGE BOARD USING A METAL BASE

AMENDMENT UNDER 37 C.F.R. § 1.111

Commissioner for Patents
Washington, D.C. 20231

Sir:

In response to the Office Action dated December 27, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel non-elected claims 18-41 without disclaimer and without prejudice to the filing of a divisional application directed to these canceled claims.

Please enter the following amended claim:

1. (Amended) A semiconductor package board comprising:
a metal base plate having an opening suited for receiving therein a semiconductor chip;
and
a multilayer wiring film formed on said metal base plate,

TC 2800 MAIL ROOM
MAR 31 2003

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